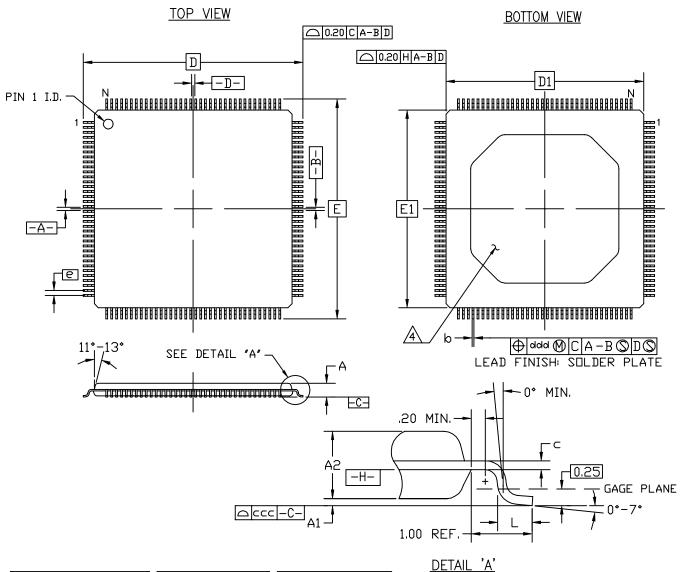
## TQFP (TQ100, TQ144, TQ176) Packages HQFP (Heat Sink) (HT100, HT144, HT176) Packages



TQ/HT100					TQ/HT144				TQ/HT176			
	MILLIMETERS				MILLIMETERS				MILLIMETERS			
Į	MIN.	N□M.	MAX.		MIN.	N□M.	MAX.		MIN.	N□M.	MAX.	
Α	~x	1	1.60		~	$\sim$	1.60		~	~	1.60	
A <sub>1</sub>	0.05	~~	0.15		0.05	0.10	0.15		0.05	0.10	0.15	
Az	1.35	1.40	1.45		1.35	1.40	1.45		1.35	1.40	1.45	
D/E	16.00 BSC				22.00 BSC				26.00 BSC			
D <sub>1</sub> /E <sub>1</sub>	14.00 BSC				20.00 BSC				24.00 BSC			
L	0.45	0.60	0.75		0.45	0.60	0.75		0.45	0.60	0.75	
e	0.50 BSC				0.50 BSC				0.50 BSC			
b	0.17	0.22	0.27		0.17	0.22	0.27		0.17	0.22	0.27	
c	0.09	~x	0.20		0.09	$\sim$	0.20		0.09	$\sim$	0.20	
ccc	~~	~~	0.08		N	$\sim$	0.08		~	~	0.08	
ddd	~~	74	0.08		~	~	0.08		~~	$\sim$	0.08	
N	100				144				176			
REF.	JEDEC MS-026-BED				JEDEC MS-026-BFB				JEDEC MS-026-BGA			

## NOTE:

- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5-1982
- DIMENSION D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.
- 3. PACKAGE TOP DIMENSION MAY BE SMALLER THAN THE BOTTOM DIMENSION BY 0.15mm.
- THE SAME PACKAGE DIMENSIONS APPLY FOR THERMALLY ENHANCED PRODUCTS. HEAT SINK IS ADDED. THE PACKAGE CODE IS "HT".

100, 144, 176-PIN TQFP/HEAT SINK TQFP (TQ/HT100, 144, 176)

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